



PATENT

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF : Jennie S. HWANG
FOR : **LEAD-FREE SOLDER
COMPOSITIONS**
SERIAL NO. : 10/056,667
FILED : October 29, 2001
ATTORNEY DOCKET NO. : RJM 2 0062

Cleveland, Ohio 44114-2518
February 13, 2002

INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner of Patents
Washington, D.C. 20231

Dear Sir:

Applicant submits herewith patents, publications or other information of which she is aware, which she believes may be material to the examination of the above-identified application and in respect of which there may be a duty to disclose in accordance with 37 C.F.R. 1.56.

This Information Disclosure Statement is not intended to constitute an admission that any patent, publication or other information referred to herein or submitted herewith is "prior art" for this invention unless specifically designated as such.

In accordance with 37 C.F.R. 1.97(g) and (h), the filing of this Information Disclosure Statement shall not be construed to mean that a search has been made or that no other material information as defined in 37 C.F.R. 1.56(b) exists.

Copies of the references listed on enclosed Form PTO-1449 are enclosed.

It is respectfully requested that the attached documents be considered and officially cited in examination of this application.

Respectfully submitted,

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I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to Assistant Commissioner for Patents, Washington, DC 20231, on 2/14/02


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